



Docket No.: 20135-00311-US  
(PATENT)

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
William E. Bernier, et al.

Conf. No.: 1044

Application No.: 09/687,524

Group Art Unit: 1725

Filed: October 12, 2000

Examiner: Jonathan J. Johnson

For: SOLDER PROTECTIVE COATING AND  
FLUXLESS JOINING OF FLIP CHIP DEVICES  
ON LAMINATES WITH PLATED SOLDER

**SUBMISSION OF FORMAL DRAWINGS**

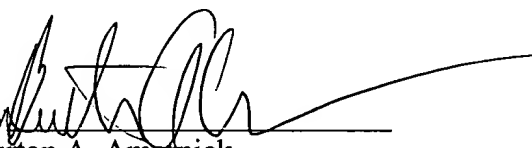
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In accordance with the Notice of Allowability mailed January 27, 2003, Applicants submit herewith 1 sheets of formal drawings of Figs. 1A-1D.

Dated: February 13, 2003

Respectfully submitted,

By   
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